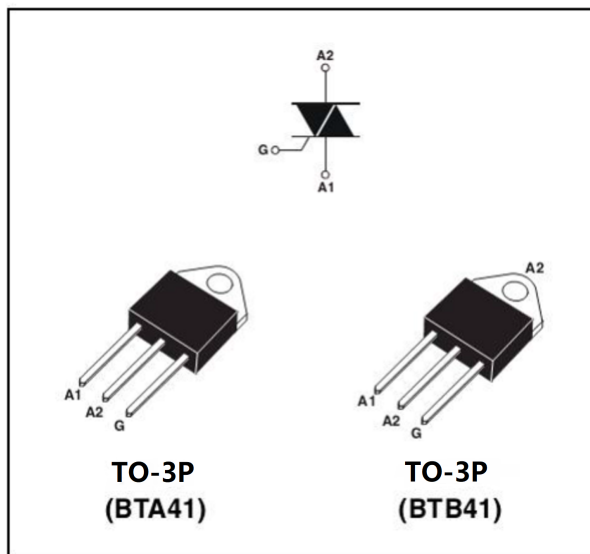


• Product features and main uses:

NPNPN five-layer structure of silicon bidirectional devices; with independent intellectual property rights of single-sided digging technology, table glass passivation process; multi-layer metallized electrodes on the back; with high blocking voltage and high temperature stability.

Mainly used in:

vacuum cleaners, power tools and other motor speed controllers; solid state relays; heating controllers (temperature regulation); other phase control circuits.



•Characteristics

Table 1. Absolute maximum ratings ($T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise stated)

Symbol	Parameter name			value	Unit
$I_{T(RMS)}$	RMS on-state current (full sine wave)	BTA BTB	$T_c=80^{\circ}\text{C}$ $T_c=90^{\circ}\text{C}$	41	A
I_{TSM}	Non repetitive surge peak on-state current (full cycle, T_j initial = $25\text{ }^{\circ}\text{C}$)	F=50HZ $t_p=20\text{ms}$		410	A
I^2t	I^2t value for fusing	$t_p=10\text{ms}$		880	A^2S
di/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $t_r \leq 100\text{ ns}$	$T_j=125^{\circ}\text{C}$		50	A/us
V_{DRM}/V_{RRM}	Off state repetitive peak voltage Reverse repetitive peak voltage	$T_j=25^{\circ}\text{C}$		1600	V
I_{GM}	Peak gate current	$t_p=20\mu\text{s}$	$T_j=125^{\circ}\text{C}$	8	A
$P_{G(AV)}$	Average gate power dissipation	$T_j=125^{\circ}\text{C}$		1	W
T_{stg} T_j	Storage junction temperature range Operating junction temperature range			$-40\text{to}+150$ $-40\text{to}+125$	$^{\circ}\text{C}$

●Table 2. Electrical characteristics ($T_j = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)
--3 quadrants

Symbol	Name and test conditions	Quadrant	Range	value	Unit
I _{GT}	V _D =12V R _L =100Ω	I II III	MAX	≦50	mA
V _{GT}			MAX	1.5	V
V _{GD}	V _D = V _{DRM} , R _L = 3.3 kΩ, T _j = 125 °C		MIN	0.2	V
I _H	I _T =0.5A		MAX	60	mA
I _L	I _G =1.2I _{GT}		MAX	60	mA
				100	
dv/dt	V _D =2/3V _{DRM} T _j =125℃		MIN	550	V/us
(dv/dt) _c	T _j =125℃		MIN	10	V/us

●Table 3. Electrical characteristics ($T_j = 25\text{ }^{\circ}\text{C}$, unless otherwise specified) - Standard Triac--- 4 quadrants

Symbol	Name and test conditions	Quadrant	Range	value		Unit
I_{GT}	$V_D=12V \quad R_L=100\Omega$	I II III IV	MAX	I、II、III	≤ 50	mA
				IV	≤ 120	
V_{GT}	MAX		1.5		V	
V_{GD}	$V_D = V_{DRM}, R_L = 3.3 \text{ k}\Omega, T_j = 125\text{ }^{\circ}\text{C}$		MIN	0.2		V
I_H	$I_T=0.5A$		MAX	80		mA
I_L	$I_G=1.2I_{GT}$	I , II ,III	MAX	80		mA
		IV		160		
dv/dt	$V_D=2/3V_{DRM} \quad T_j=125^{\circ}\text{C}$		MIN	550		V/us
$(dv/dt)_c$	$T_j=125^{\circ}\text{C}$		MIN	10		V/us

●Static parameters

Symbol	Parameter name			value	Unit
V_{TM}	$I_{TM}= 60A$	$T_j=25^{\circ}C$	MAX	1.55	V
V_{T0}	threshold on-state voltage	$T_j=125^{\circ}C$	MAX	0.86	V
R_d	Dynamic resistance	$T_j=125^{\circ}C$	MAX	6.4	mΩ
I_{DRM} I_{RRM}	Repetitive peak off-state current Repetitive peak reverse current	$T_j=25^{\circ}C$	MAX	10	uA
		$T_j=125^{\circ}C$		2	mA
$R_{th(j-c)}$	Junction to ambient	BTA		0.9	$^{\circ}C/W$
		BTB		0.6	

BTA41A,BTB41A characteristic curve

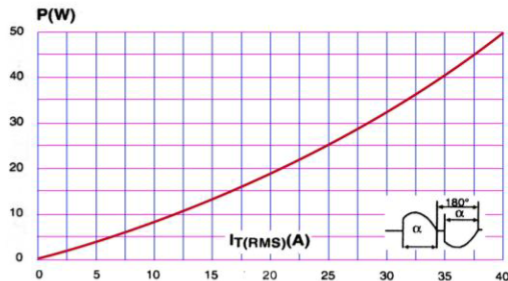


FIG.1: Maximum power dissipation versus RMS on-state current(180°C)

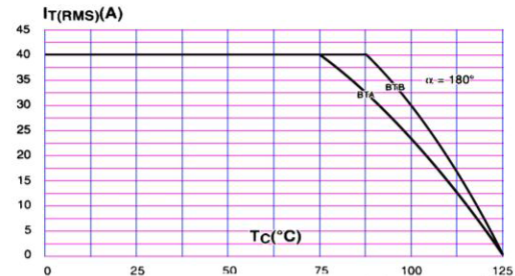


FIG.2: RMS on-state current versus case

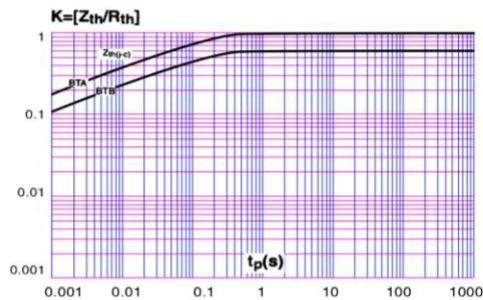


FIG.3: Transient thermal impedance curves

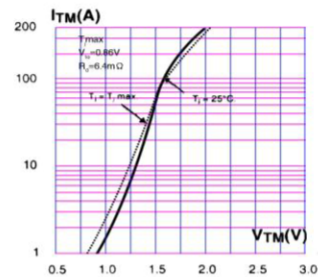


FIG.4: On-state characteristics

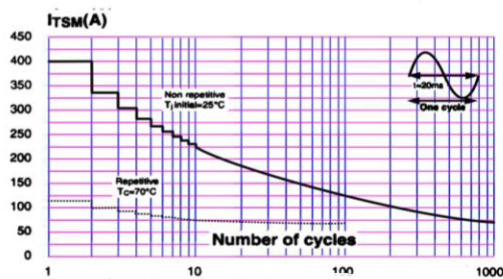


FIG.5: Surge peak on-state current versus number of cycles

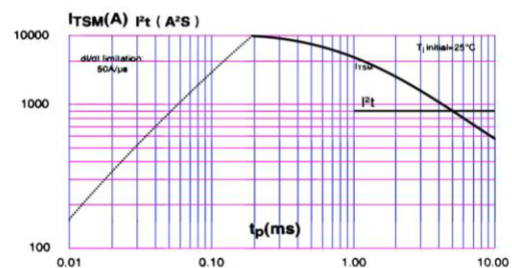


FIG.6: ITSM-t, I2t-t

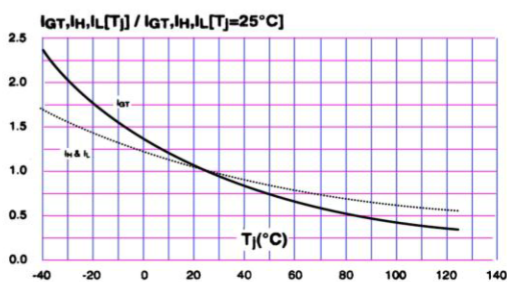
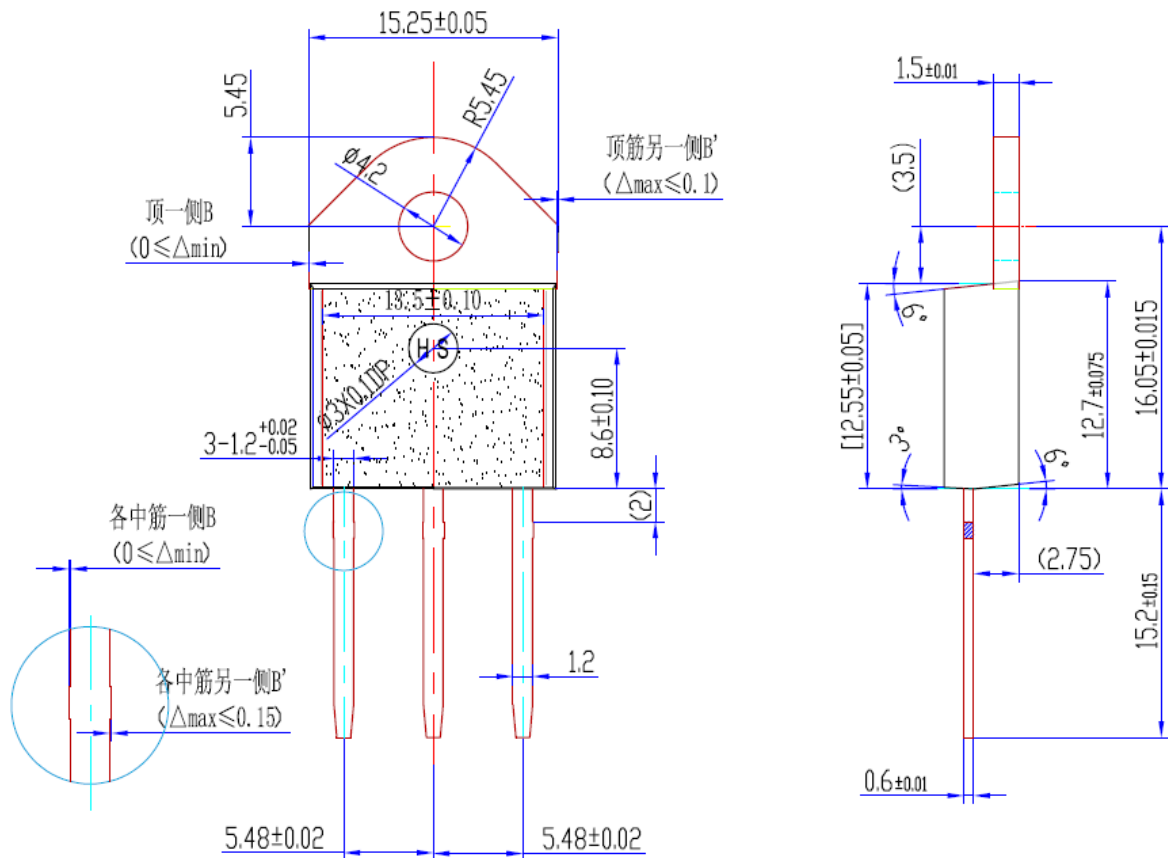


FIG.7: Gate trigger characteristic curves

●TO-3P Dimensional drawing:

Unit: mm (± 0.1)

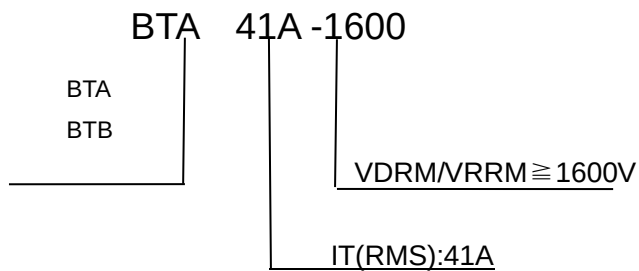




●Product Marking Comments:

XXXXX_____Production batch number

LGE _____Company Logo



BTA: Insulation type

BTB: Non insulated type

